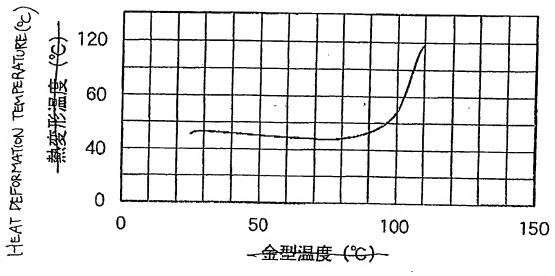
Fig. 1

## <del>「成形時の金型温度と熱変形温度の関係</del>-



MOLD TEMPERATURE (&)

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AND...... Filing Date: February 27, 2004 Mark Boland 202-663-7949